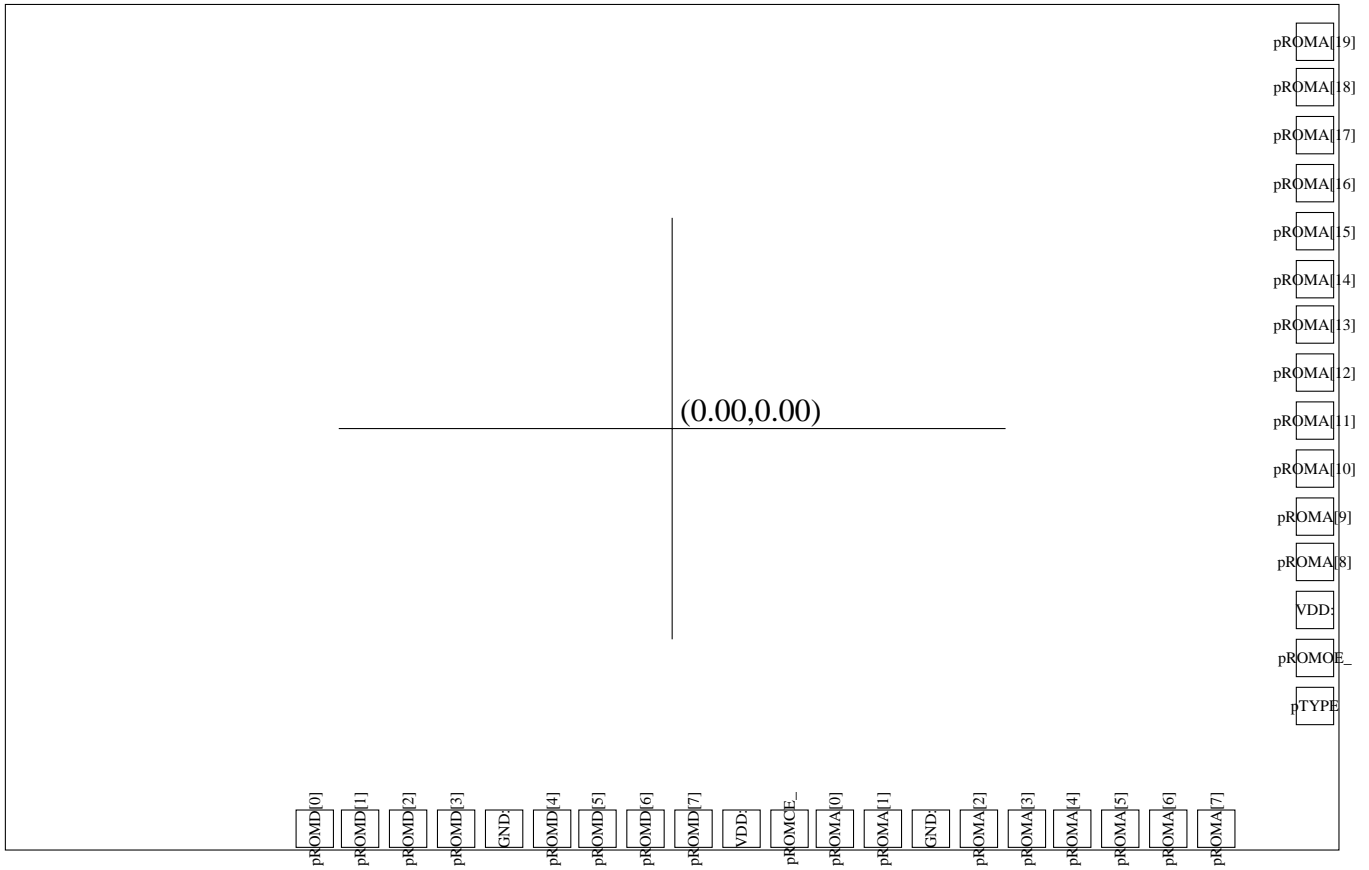


SONIX TECHNOLOGY CO., LTD.

BONDING PAD LOCATION



CHIP SIZE : X=3090um, Y=1965um

SR008